

L Number	Hits	Search Text	DB	Time stamp
1	39	(KCN with (clean\$3 or rins\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 09:01
2	63	(KCN with (etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 09:02
3	45	(KCN with (etch\$3)) and (copper or nickel or ni or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 09:18
4	39	(KCN with (etch\$3)) and (copper or cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:55
5	26	(KCN with ("20%"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 09:19
6	149	(216/14).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:49
7	1124	(216/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:43
8	22	((216/13).CCLS.) and (cyanide or KCN)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:43
9	215	(216/16).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:50
10	433	(216/17).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:52
11	24	(216/21).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:59
12	562	(228/103).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:55
13	622	(228/119).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 10:55
14	949	(216/100).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 11:00

15	467	(216/105).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 11:01
16	35	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 11:02
17	21	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN) and (Ni or Nickel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 11:03
18	29	((216/100).CCLS.) or ((216/105).CCLS.) and (cyanide or KCN) and (Cu or copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/29 11:03
	191	((nickel and gold) adj layer).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:43
	39	((nickel and gold) adj layer) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:43
	792	((nickel and gold and copper) and etch\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:58
	9	((nickel and gold and copper) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:48
	212	((nickel and gold and copper) and etch\$3 and pad\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:47
	6	((nickel and gold and copper) and rework\$3).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:48
	9	((bond\$3 adj pad\$1) and blasting).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:54
	6	((bond\$3 adj pad\$1) and cyanide).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:50
	14	((gold or nickel or copper) and pad\$1 and blasting).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:54
	634	((nickel and gold and copper) and pad\$1).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 12:58



	17	(bond\$3 adj pad\$1) and (etch\$3 same cyanide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
	88	(bond\$3 adj pad\$1) and (etch\$3 same pH)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
	17	(bond\$3 adj pad\$1) and (etch\$3 same alkaline same pH)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:14
	1	((copper adj pad\$1) and rework\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:43
	1	((copper adj pad\$1) and blast\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 08:43
	39	nickel same copper same etch\$3 same cyanide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 09:40
	16	etchant\$1 with nickel with strip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:02
	1	etchant\$1 with nickel with pH with ("13" or "12" or "14")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:03
	9	etchant\$1 with nickel with pH	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:05
	6	((nickel with etchant) and ph).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:18
	4	(nickel near3 etchant\$1) and (Ph adj2 ("12" or "13" or "14"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 10:25
	64	diethyldithiocarbamate with ethylenediamine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:47
	3	diethyldithiocarbamate with ethylenediamine with (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:49
	28	enthone and ethylenediamine and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:09

	100	enthone.as. and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:10
	21	enthone.as. and nickel and strip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:23
	5	diethyldithiocarbamate same ethylenediamine same (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:18
	7	enthone.as. and nickel and strip\$3 and copper and steel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:55
	3193	ethylenediamine with (hydroxide or sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:49
	33	ethylenediamine with (hydroxide and sulfonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:49
	10	(ethylenediamine with (hydroxide and sulfonic)) and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:49
	9	enthone.as. and nickel and sulfonate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:55
	16	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 11:59
	2	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375")).PN.) and nickel and etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 12:00
	10	((("4007037") or ("4502924") or ("5489410") or ("5549809") or ("5682415") or ("5768339") or ("5858557") or ("6083375")).PN.) and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/28 12:00